4.(Amended) An electronic component mounting method as claimed in claims 1, wherein

the insulating resin (6m) of the anisotropic conductive layer is in a liquid form when applied to the board, and after semi-solidifying the resin by hardening the liquid of the applied insulating resin with the board placed in a furnace (503) or by pressurizing the liquid of the applied insulating resin by means of a heated tool (78) after the application to the board, the electronic component is mounted on the board.

6.(Amended) An electronic component mounting method as claimed in claim 1, wherein the electronic component (1) has a plurality of electrodes (2), a solid anisotropic conductive film sheet (10) that has a configurational dimension smaller than an outline dimension (OL) defined by joining the plurality of electrodes (2) of the electronic component (1) is stuck as the anisotropic conductive layer to the circuit board (4) before the positional alignment and thereafter subjected to the positional alignment, and at the bonding time, the insulating resin interposed between the electronic component and the circuit board is hardened by pressurizing the electronic component against the circuit board with heat applied to the anisotropic conductive film sheet (10) while concurrently correcting the warp of the circuit board, so that the electronic component is bonded to the circuit board.

7.(Amended) An electronic component mounting method as claimed in claim 1, wherein the gold bump that has an approximately conically shaped tip is formed on the electrode of the electronic component by means of the capillary that has a chamfer angle (θc) of not greater than 100° when a gold ball (96a) is formed by an electric spark at a tip of a gold wire (95) similarly to the wire bonding in forming the bump on the electronic component and a tip shape provided with no flat portion to be brought in contact with the gold ball.

12.(Amended) An electronic component mounting method as claimed in claim 10, wherein

the device (93, 193) for forming the gold ball (96a) has the capillary, which has a tip shape provided with no flat portion to be brought in contact with the gold ball and of which a chamfer angle (θc) is not greater than 100°, and the gold bump that has an approximately conically shaped tip is formed on the electrode of the electronic component by the capillary.

14.(Amended) An electronic component mounting method as claimed in claim 1, wherein a mean particle diameter of the inorganic filler mixed with the insulating resin of the anisotropic conductive layer is not smaller than 3 μm.

15.(Amended) An electronic component mounting method as claimed in claim 1, wherein the inorganic filler mixed with the insulating resin of the anisotropic conductive

layer is comprised of at least two types of inorganic fillers (6f-1, 6f-2) that have a plurality of different mean particle diameters, and a mean particle diameter of one inorganic filler (6f-1) out of at least two types of inorganic fillers is not less than two times different from a mean particle diameter of the other inorganic filler (6f-2) out of at least two types of inorganic fillers.

16.(Amended) An electronic component mounting method as claimed in claim 1, wherein the anisotropic conductive layer has a portion brought in contact with either the electronic component or the board, the portion having a smaller amount of inorganic filler than that of the other portion.

20.(Amended) An electronic component mounting method as claimed in claim 1, wherein the bump is a bump formed by plating or printing.

21.(Amended) An electronic component unit as claimed in claim 18, wherein the bump is a bump formed by plating or printing.

22.(Amended) An electronic component mounting method as claimed in claim 1, wherein the anisotropic conductive layer is provided by mixing the solid insulating resin mixed with the inorganic filler with a conductive particle (10a) that has a mean diameter greater than a mean particle diameter of the inorganic filler.